

Highlights

- Excellent surface finish, lifetime, and flatness

Standard CMP backing film

DF200

The original pad material created both for polishing and backing films, the DF200 continues to be popular film across many industries, including semiconductor, optics, and specialty substrates. First developed by Rodel at the inception of waxless fixturing, the DF200 is a poromeric film buffed such that it has an open, tube-like pore structure. This structure compresses to absorb flatness variations on both the back-side of the wafer, as well as the polishing head itself. In addition, it will rebound to its original thickness over a long period of time, producing greater flatness throughout the lifetime of the film. Finally, the film features superior flatness results when used in a template, as wafers held in place by water tension are still able to rotate within the pocket.

When used as a final polishing pad, the DF200 construction quality yields excellent surface finish, lifetime, and flatness.

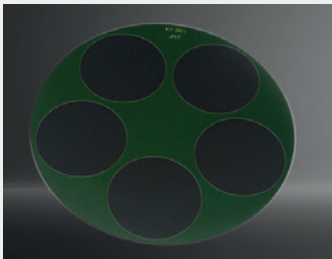
DF200 is also commonly used as gasket material or a carrier film. It is easily cut to any size, and laser-cut vacuum holes may also be implemented.

Backing film	Compression	Deflection	TTV	Pore Structure / Wafer spin	Substrate
NTA CHOIS	9.00 %	0.053 mm	Good > 5 μ	Open / Yes	Silicon, various
NTA DF200	10.60 %	0.065 mm	Best NTA ~4 μ	Open / Yes	Silicon, sapphire, various (all)
NTA E310	5.75 %	0.041 mm	Good	Open / No	Silicon carbide
NTA WB20	3.45 %	0.016 mm	Good	Open / No	Ceramic, various

The data presented is a statistical representation for comparison purposes. The values are not necessarily representative of the COA specifications.



DF200 film material is a versatile poromeric with many potential applications.



DF200 is the film of choice for template construction, offering excellent lifetime, durability, and wafer protection.



Pureon offers a wide range of customized solutions. More information can be found on www.pureon.com/products/overview

Product specifications

- Base material Poromeric
- Shelf life 12 months
- Applications Template construction, carrier films, gasket material

Application recommendations

- Handling Apply only to a clean, dry surface at room temperature. If an appropriate solvent, such as isopropyl alcohol, is used to clean the platen after a pad removal, allow the platen to dry completely and return to room temperature before applying a new pad. Solvents remaining on the platen or an unusually cold platen will lower PSA adhesion.

When applying the pad to the platen, peel the release liner from one edge of the pad. Fold liner back approximately two inches. Align the pad with the edge of the platen and adhere. In one continuous movement, slowly peel the remaining release liner off the pad while pressing the pad down on the platen. The application should be smooth and uniform with even pressure from the pad mounting tool (such as a flat disk or hand roller).

Do not try to reposition pads with PSA adhesive.

- Storage Product should be stored and transported in the original packaging. The product should be stored in temperatures between 10 °C to 24 °C (50 °F to 75 °F) and < 50 % humidity. Exposure for six (6) months or less to conditions between -17 °C to 48 °C (0 °F and 120 °F) and / or at relative humidity of up to 100 % will not impact the product performance as long as the release liner remains intact and attached to the PSA. If the product is exposed to temperatures and humidity outside the recommended conditions, it may still be acceptable for use. In all cases, the product should be allowed to return to normal room temperatures prior to use.

- Disposal Dispose of in accordance with all applicable local regulations.

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